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Kind regards,

Team Nexperia



# PDTA114YMB

PNP resistor-equipped transistor; R1 = 10 k $\Omega$ , R2 = 47 k $\Omega$

Rev. 1 — 16 May 2012

Product data sheet

## 1. Product profile

### 1.1 General description

PNP Resistor-Equipped Transistor (RET) in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

NPN complement: PDTC114YMB.

### 1.2 Features and benefits

- 100 mA output current capability
- Reduces component count
- Built-in bias resistors
- Reduces pick and place costs
- Simplifies circuit design
- AEC-Q101 qualified
- Leadless ultra small SMD plastic package
- Low package height of 0.37 mm

### 1.3 Applications

- Low-current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications
- Mobile applications

### 1.4 Quick reference data

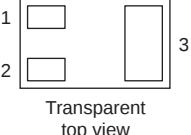
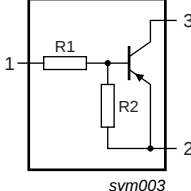
Table 1. Quick reference data

| Symbol           | Parameter                 | Conditions               | Min | Typ | Max  | Unit       |
|------------------|---------------------------|--------------------------|-----|-----|------|------------|
| V <sub>CEO</sub> | collector-emitter voltage | open base                | -   | -   | -50  | V          |
| I <sub>O</sub>   | output current            |                          | -   | -   | -100 | mA         |
| R1               | bias resistor 1 (input)   | T <sub>amb</sub> = 25 °C | 7   | 10  | 13   | k $\Omega$ |
| R2/R1            | bias resistor ratio       |                          | 3.7 | 4.7 | 5.7  |            |



2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description        | Simplified outline                                                                                                                | Graphic symbol                                                                                |
|-----|--------|--------------------|-----------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------|
| 1   | I      | input (base)       | <br>Transparent top view<br>SOT883B (DFN1006B-3) | <br>sym003 |
| 2   | G      | GND (emitter)      |                                                                                                                                   |                                                                                               |
| 3   | O      | output (collector) |                                                                                                                                   |                                                                                               |

3. Ordering information

Table 3. Ordering information

| Type number | Package    |                                                                                |         |
|-------------|------------|--------------------------------------------------------------------------------|---------|
|             | Name       | Description                                                                    | Version |
| PDTA114YMB  | DFN1006B-3 | Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm | SOT883B |

4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PDTA114YMB  | 0001 1111    |

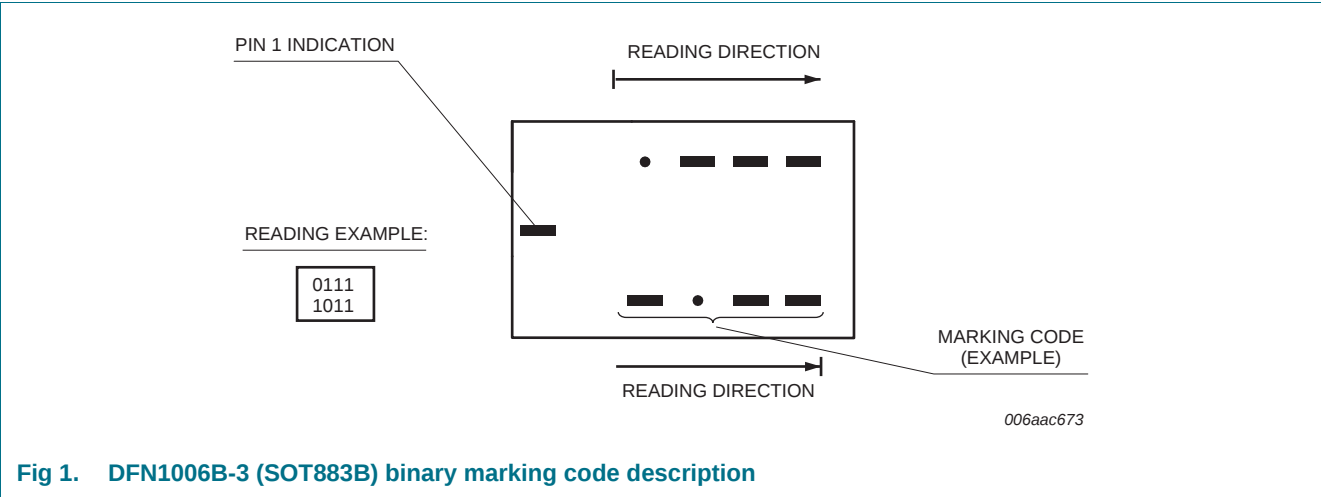


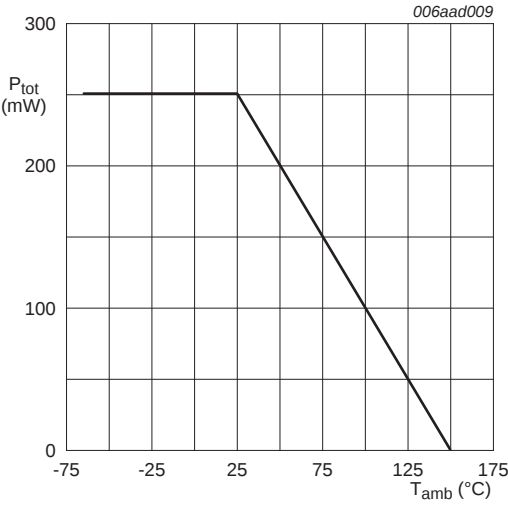
Fig 1. DFN1006B-3 (SOT883B) binary marking code description

5. Limiting values

Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter                 | Conditions                                   | Min | Max  | Unit |
|------------------|---------------------------|----------------------------------------------|-----|------|------|
| V <sub>CBO</sub> | collector-base voltage    | open emitter                                 | -   | -50  | V    |
| V <sub>CEO</sub> | collector-emitter voltage | open base                                    | -   | -50  | V    |
| V <sub>EBO</sub> | emitter-base voltage      | open collector                               | -   | -6   | V    |
| V <sub>I</sub>   | input voltage             | positive                                     | -   | 6    | V    |
|                  |                           | negative                                     | -   | -40  | V    |
| I <sub>O</sub>   | output current            |                                              | -   | -100 | mA   |
| I <sub>CM</sub>  | peak collector current    | pulsed; t <sub>p</sub> ≤ 1 ms                | -   | -100 | mA   |
| P <sub>tot</sub> | total power dissipation   | T <sub>amb</sub> ≤ 25 °C <a href="#">[1]</a> | -   | 250  | mW   |
| T <sub>j</sub>   | junction temperature      |                                              | -   | 150  | °C   |
| T <sub>amb</sub> | ambient temperature       |                                              | -65 | 150  | °C   |
| T <sub>stg</sub> | storage temperature       |                                              | -65 | 150  | °C   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



FR4 PCB, standard footprint

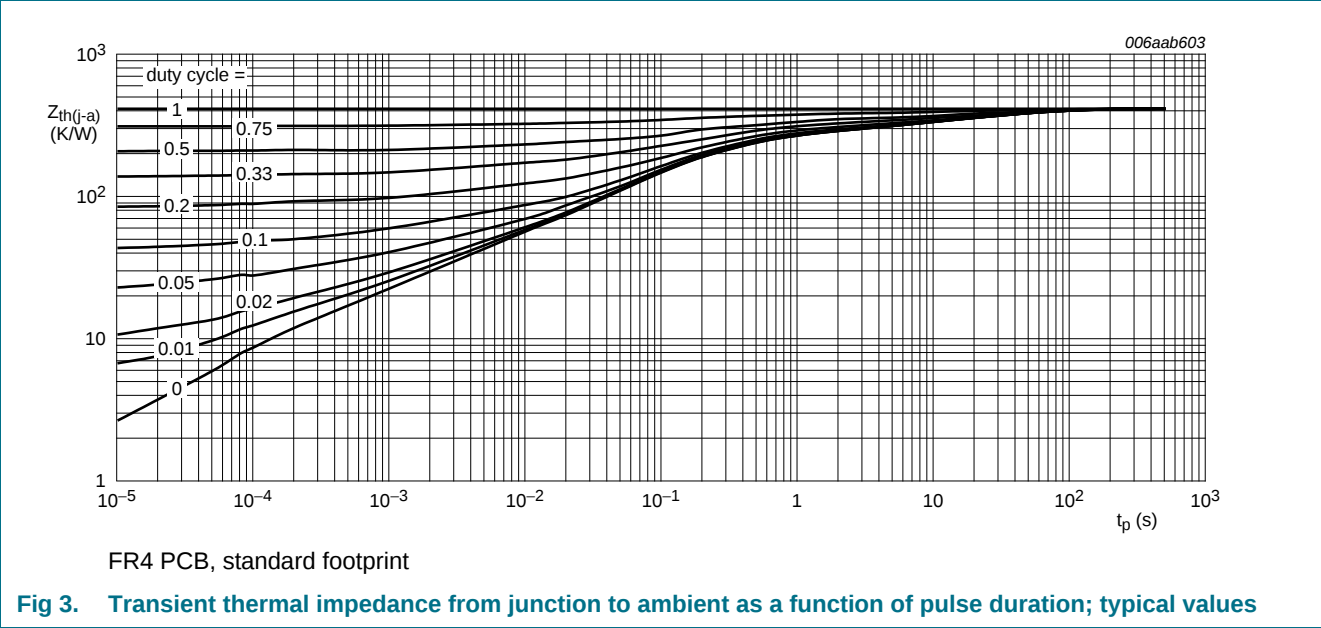
Fig 2. Power derating curve for DFN1006B-3 (SOT883B)

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol        | Parameter                                   | Conditions  | Min | Typ | Max | Unit |
|---------------|---------------------------------------------|-------------|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | -   | -   | 500 | K/W  |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

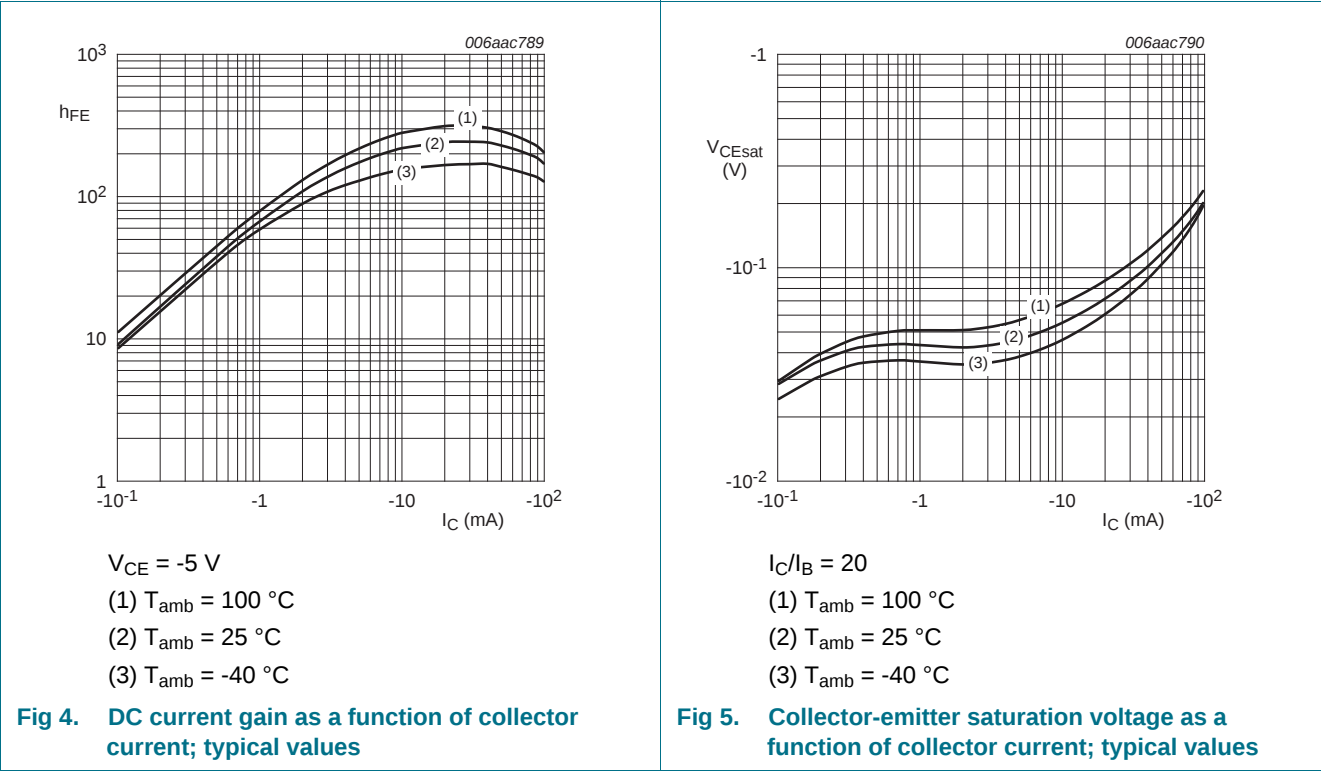


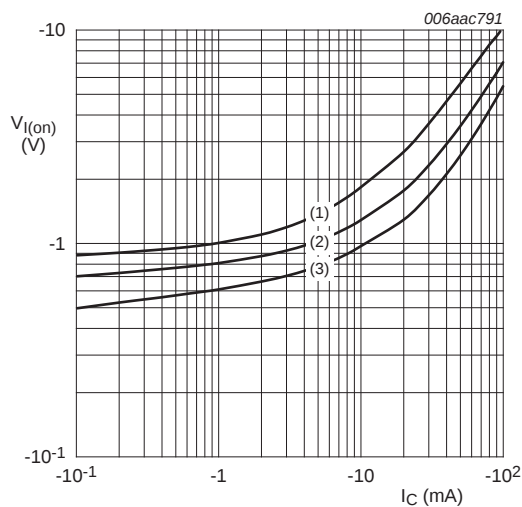
7. Characteristics

Table 7. Characteristics

| Symbol       | Parameter                            | Conditions                                                                                                                            | Min  | Typ  | Max  | Unit          |
|--------------|--------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------|------|------|------|---------------|
| $I_{CBO}$    | collector-base cut-off current       | $V_{CB} = -50\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                                 | -    | -    | -100 | nA            |
| $I_{CEO}$    | collector-emitter cut-off current    | $V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                                 | -    | -    | -1   | $\mu\text{A}$ |
|              |                                      | $V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_j = 150\text{ }^{\circ}\text{C}$                                                    | -    | -    | -5   | $\mu\text{A}$ |
| $I_{EBO}$    | emitter-base cut-off current         | $V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                                  | -    | -    | -150 | $\mu\text{A}$ |
| $h_{FE}$     | DC current gain                      | $V_{CE} = -5\text{ V}$ ; $I_C = -5\text{ mA}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                                | 100  | -    | -    |               |
| $V_{CEsat}$  | collector-emitter saturation voltage | $I_C = -5\text{ mA}$ ; $I_B = -0.25\text{ mA}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                               | -    | -    | -100 | mV            |
| $V_{I(off)}$ | off-state input voltage              | $V_{CE} = -5\text{ V}$ ; $I_C = -100\text{ }\mu\text{A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                     | -    | -0.7 | -0.5 | V             |
| $V_{I(on)}$  | on-state input voltage               | $V_{CE} = -0.3\text{ V}$ ; $I_C = -1\text{ mA}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$                                              | -1.4 | -0.8 | -    | V             |
| R1           | bias resistor 1 (input)              | $T_{amb} = 25\text{ }^{\circ}\text{C}$                                                                                                | 7    | 10   | 13   | kΩ            |
| R2/R1        | bias resistor ratio                  |                                                                                                                                       | 3.7  | 4.7  | 5.7  |               |
| $C_C$        | collector capacitance                | $V_{CB} = -10\text{ V}$ ; $I_E = 0\text{ A}$ ; $i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$       | -    | -    | 3    | pF            |
| $f_T$        | transition frequency                 | $V_{CE} = -5\text{ V}$ ; $I_C = -10\text{ mA}$ ; $f = 100\text{ MHz}$ ; <a href="#">[1]</a><br>$T_{amb} = 25\text{ }^{\circ}\text{C}$ | -    | 180  | -    | MHz           |

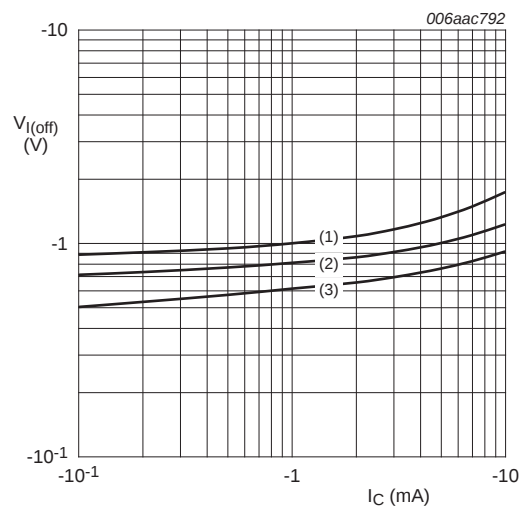
[1] Characteristics of built-in transistor.





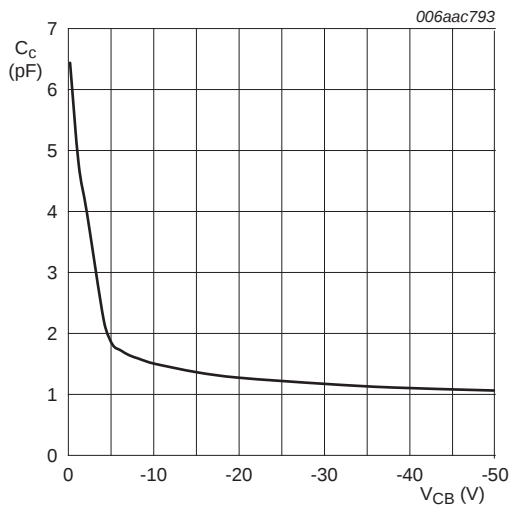
$V_{CE} = -0.3$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

Fig 6. On-state input voltage as a function of collector current; typical values



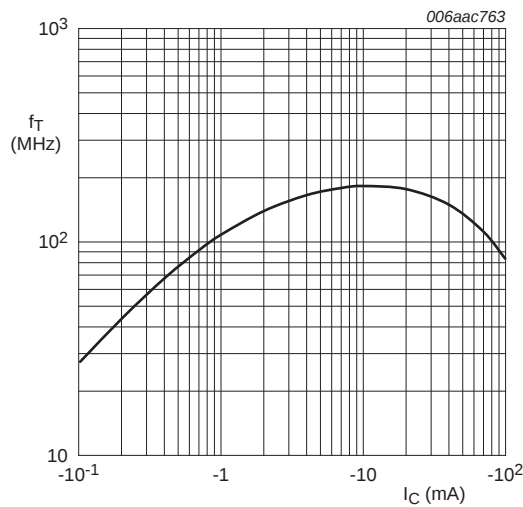
$V_{CE} = -5$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

Fig 7. Off-state input voltage as a function of collector current; typical values



$f = 1$  MHz;  $T_{amb} = 25$  °C

Fig 8. Collector capacitance as a function of collector-base voltage; typical values



$V_{CE} = -5$  V;  $T_{amb} = 25$  °C

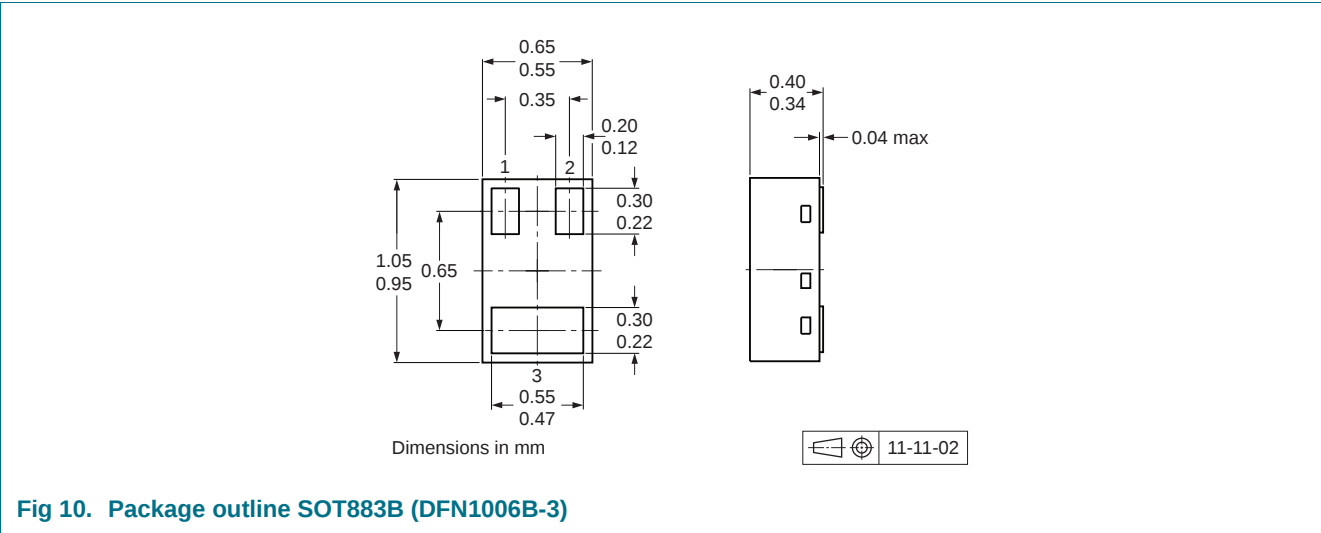
Fig 9. Transition frequency as a function of collector current; typical values of built-in transistor

8. Test information

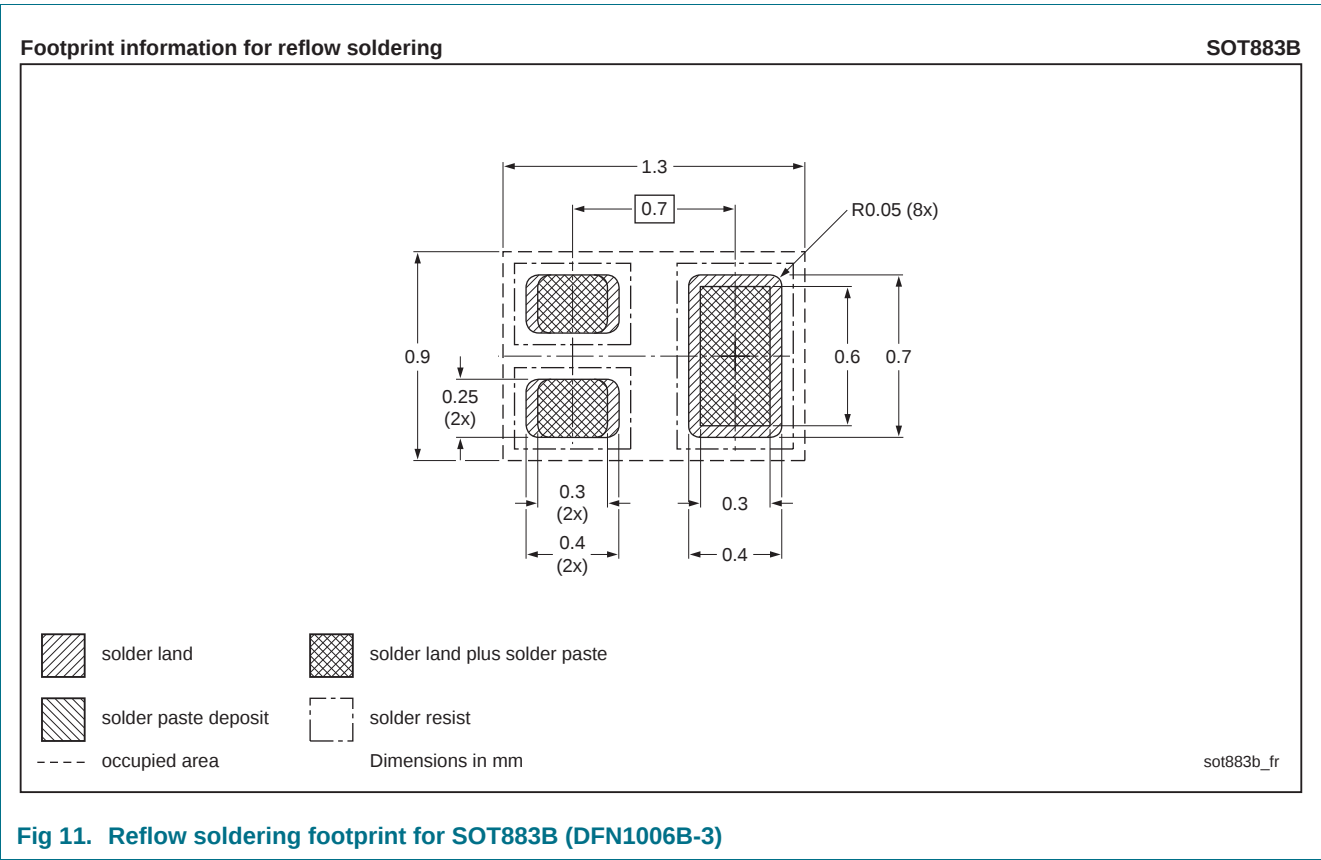
8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline



10. Soldering



11. Revision history

Table 8. Revision history

| Document ID    | Release date | Data sheet status  | Change notice | Supersedes |
|----------------|--------------|--------------------|---------------|------------|
| PDTA114YMB v.1 | 20120516     | Product data sheet | -             | -          |

## 12. Legal information

### 12.1 Data sheet status

| Document status <sup>[1] [2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|------------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet       | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet     | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet         | Production                    | This document contains the product specification.                                     |

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[2] The term 'short data sheet' is explained in section "Definitions".

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